



Material Content Data Sheet



Sales Product Name	TLE42694E			Issued	1. August 2018			
MA#	MA000969726							
Package	PG-SSOP-14-2			Weight*	83.34 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.391	2.87	2.87	28688	28688
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		413	
	non noble metal	iron	7439-89-6	0.689	0.83		8268	
wire	non noble metal	copper	7440-50-8	27.978	33.57	34.45	335701	344485
	noble metal	gold	7440-57-5	0.157	0.19	0.19	1888	1888
	encapsulation	organic material	carbon black	1333-86-4	0.098	0.12		1176
encapsulation	plastics	epoxy resin	-	4.508	5.41		54089	
	inorganic material	silicondioxide	60676-86-0	44.392	53.26	58.79	532659	587924
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11712	11712
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9210	9210
glue	plastics	epoxy resin	-	0.335	0.40		4023	
	noble metal	silver	7440-22-4	1.006	1.21	1.61	12070	16093
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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